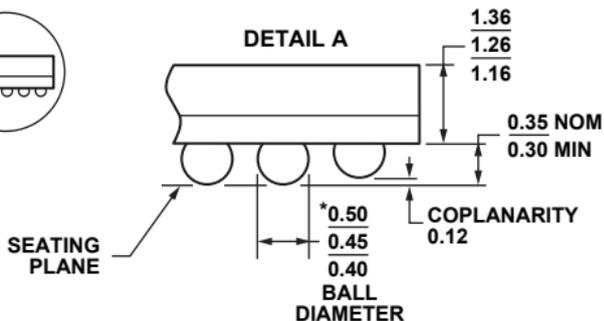
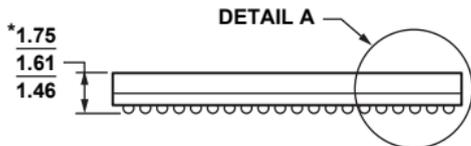
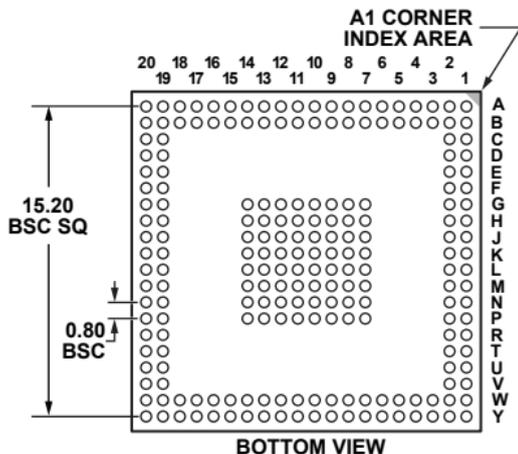
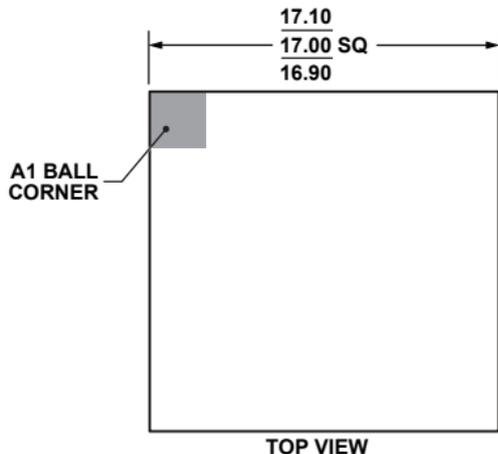


**208-Ball Chip Scale Package Ball Grid Array [CSP\_BGA]  
(BC-208-2)**

Dimensions shown in millimeters



**\*COMPLIANT TO JEDEC STANDARDS MO-205-AM WITH  
EXCEPTION TO PACKAGE HEIGHT AND BALL DIAMETER.**